

Description

The SI4214DDY-T1-E3 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

D1_{D1}_{D2}_{D2} S1_{G1}_{S2</sup>_{G2}}

SOP-8

General Features

V_{DS} = 30V I_D = 8A

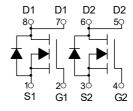
 $R_{DS(ON)} < 19m\Omega$ @ $V_{GS}=4.5V$

Application

Battery protection

Load switch

Uninterruptible power supply



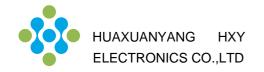
Dual N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
SI4214DDY-T1-E3	SOP-8	4842 XXX YYYY	3000

Absolute Maximum Ratings@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	30	V
V _G S	Gate-Source Voltage	<u>+</u> 20	V
I _D @T _A =25°C	Drain Current, V _{GS} @ 4.5V ³	8	А
I _D @T _A =70°C	Drain Current, V _{GS} @ 4.5V ³	5.8	А
Ірм	Pulsed Drain Current ¹	37	А
P _D @T _A =25°C	Total Power Dissipation	1.5	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
Rthj-a	Maximum Thermal Resistance, Junction- ambient ³	85	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I_D =250uA	30			V	
$\triangle BV_{DSS}/\triangle T$	BVDSS Temperature Coefficient	Reference to 25°C, I _D =1mA		0.034		V/°C	
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =7A		17	19	mΩ	
		V _{GS} =4.5V , I _D =4A	22		28	11122	
$V_{GS(th)}$	Gate Threshold Voltage	\\ -\\ -250\	1.2		2.5	V	
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		-5.8		mV/°C	
	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =25°C			1	- uA	
I _{DSS}		V _{DS} =24V , V _{GS} =0V , T _J =55°C			5	uA	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =7A		6		S	
R_g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2.5		Ω	
Qg	Total Gate Charge (4.5V)			6			
Q _{gs}	Gate-Source Charge	V _{DS} =15V , V _{GS} =4.5V , I _D =7A		2.5		nC	
Q_{gd}	Gate-Drain Charge			2.1			
T _{d(on)}	Turn-On Delay Time			2.4			
T _r	Rise Time	V_{DD} =15V , V_{GS} =10V , R_{G} =3.3 Ω		7.8			
$T_{d(off)}$	Turn-Off Delay Time	I _D =7A		22		ns	
T _f	Fall Time			4			
C _{iss}	Input Capacitance			572			
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		80		pF	
C _{rss}	Reverse Transfer Capacitance			65			

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,5}	\/ =\/ =0\/ Force Current			7.3	Α
I _{SM}	Pulsed Source Current ^{2,5}	V _G =V _D =0V , Force Current			37	Α
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V
t _{rr}	Reverse Recovery Time			20		nS
Qrr	Reverse Recovery Charge	IF=7A,dI/dt=100A/µs,TJ=25°C		1.1		nC

Note

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V, L=0.1mH, I_{AS} =21A
- 4.The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

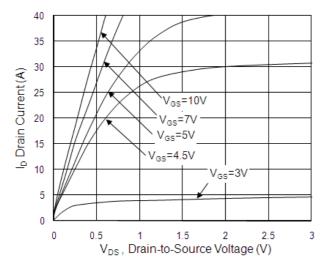


Fig.1 Typical Output Characteristics

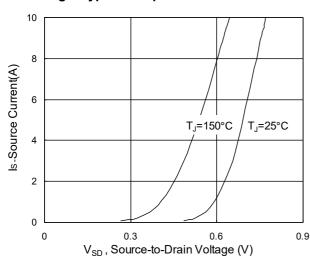


Fig.3 Forward Characteristics Of Reverse

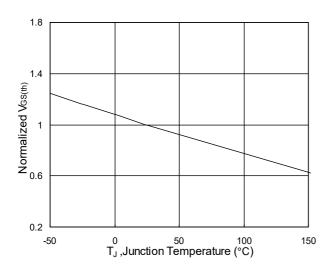


Fig.5 Normalized V_{GS(th)} vs. T_J

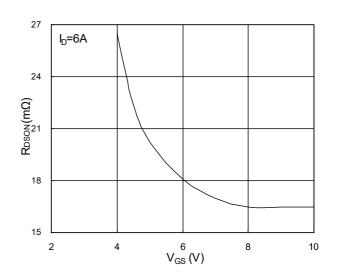


Fig.2 On-Resistance vs. G-S Voltage

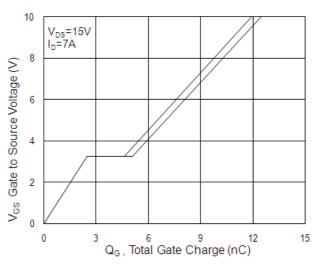


Fig.4 Gate-Charge Characteristics

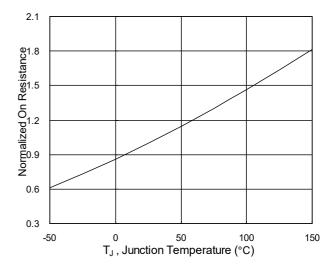
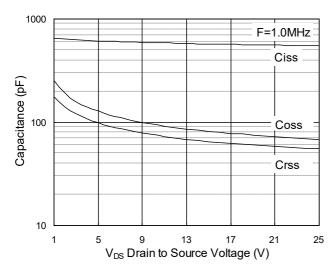


Fig.6 Normalized R_{DSON} vs. T_J



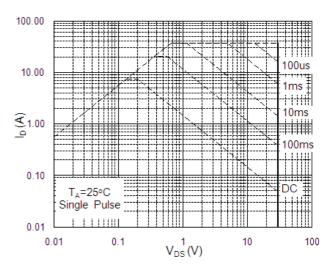


Fig.7 Capacitance

Fig.8 Safe Operating Area

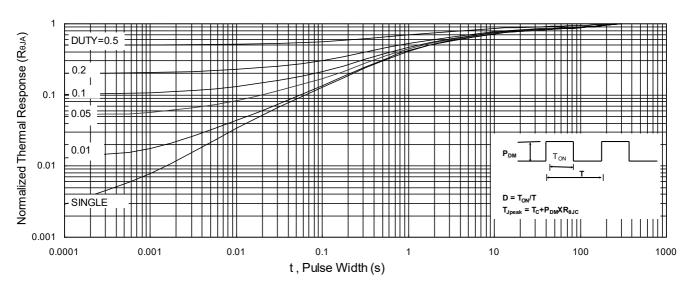


Fig.9 Normalized Maximum Transient Thermal Impedance

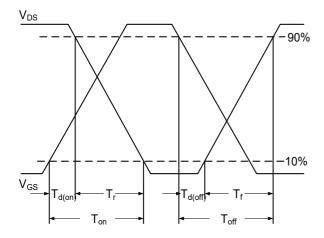


Fig.10 Switching Time Waveform

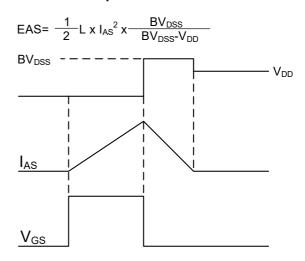
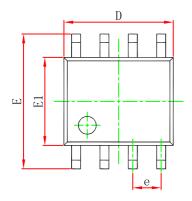
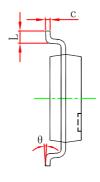


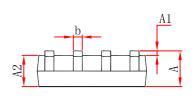
Fig.11 Unclamped Inductive Switching Waveform



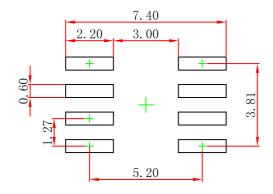
SOP-8 Package Outline Dimensions







Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
A	1. 350	1.750	0.053	0.069	
A1	0.100	0. 250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
c	0.170	0.250	0.007	0.010	
D	4.800	5.000	0.189	0. 197	
e	1. 270 (BSC)	0.050 (BSC)		
E	5.800	6.200	0.228	0. 244	
E1	3.800	4.000	0.150	0. 157	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	



- Note:
 1.Controlling dimension: in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.

Dual N-Channel Enhancement Mode MOSFET

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